

Title (en)
MODULE WITH INTEGRATED CIRCUIT COMPRISING A SHAPING DEVICE

Title (de)
EINE FORMUNGSEINRICHTUNG ENTHALTENDER MODUL MIT INTEGRIERTER SCHALTUNG

Title (fr)
MODULE A CIRCUIT INTEGRE COMPORTANT UN ORGANE DE CONFORMATION

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Application
EP 97952993 A 19971223

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Abstract (en)
[origin: FR2758005A1] The invention concerns a module with integrated circuit comprising an integrated circuit (2) arranged on one face of a insulating substrate film (1) and connected to conductive ranges (3) arranged on the opposite face of the substrate film (1) by linking elements (4) extending in holes (5) of the substrate film (1), and a shaping device (6) comprising a base (7) fixed in the substrate film (1) and a wall (8) inclining towards the inside of the shaping device (6).

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